

Parker Chomerics Tecknit® 0192/0193 Conductive Silicone Sealant/Adhesive

Category : Polymer , Adhesive , Thermoset , Silicone

Material Notes:

Comments: Rec. bond line thickness: < 0.4 mm; flexible past. Typical Applications: Bonding Ag/Cu elastomer gaskets; thin bond gap. Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-Tecknit-01920193-Conductive-Silicone-SealantAdhesive.php

Physical Properties	Metric	English	Comments
Specific Gravity	3.80 g/cc	3.80 g/cc	
Volatile Organic Compounds (VOC) Content	0.00 g/l	0.00 g/l	
Thickness	254 microns	10.0 mil	

Mechanical Properties	Metric	English	Comments
Shear Strength	>= 1.38 MPa	>= 200 psi	

Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.040 ohm-cm	<= 0.040 ohm-cm	

Processing Properties	Metric	English	Comments
Cure Time	10100 min @Temperature 24.0 °C	168 hour @Temperature 75.2 °F	
Shelf Life	9.00 Month	9.00 Month	

Descriptive Properties	Value	Comments
Filler	Ag/Cu	
Resin System	Silicone	

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